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In the Claims:

Cancel Claims 6-11 without prejudice or disclaimer
subject to the restriction requirement.

Add the following new claims:

12. A method for insulating a bonding wire
comprising the following steps:

- (a) attaching a bonding wire to a bond pad with a bond tool;
- (b) pumping an insulating liquid through a nozzle orifice coupled to the bond tool to apply a uniform thickness of the insulating liquid on the bonding wire; and
- (c) drawing the bonding wire through the bond tool from the bond pad toward a package lead while pumping the insulating liquid.

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13. The method of Claim 12 further comprising the step of ceasing to pump the insulating liquid.

14. The method of Claim 13 further comprising the step of attaching the bonding wire to the package lead after ceasing to pump the insulating liquid.

15. The method of Claim 14 further comprising the step of solidifying the insulating liquid on the bonding wire after attaching the bonding wire to the package lead.

16. The method of Claim 15 wherein the step of solidifying the insulating liquid comprises one of heating the bonding wire and exposing the bonding wire to ultraviolet

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radiation.

*A1
Canceled*
17. The method of Claim 12 further comprising repeating steps (a), (b), and (c) to complete a microelectronic package.

REMARKS

Claims 6-11 have been canceled subject to the restriction requirement.

New Claims 12-17 have been added.

Claims 1-5 and 12-17 remain pending in the application.

Applicant respectfully requests reconsideration and examination of Claims 1-5 and 12-17 in view of the amendments above and the arguments below.

By way of this response, Applicant has made a diligent effort to place the claims in condition for allowance. However, should there remain any outstanding issues that require adverse action, it is respectfully requested that the examiner telephone Leo J. Peters at (408)433-4578 so that such issues may be resolved as expeditiously as possible.

Claims 1-5 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Manteghi, U.S. Patent No. 6,046,075 (Manteghi) in view of Marrs, U.S. Patent No. 5,795,818 (Marrs). Applicant traverses the rejection as follows.

Regarding Claim 1, the rejection errs in alleging that Manteghi discloses coating the bonding wire with an insulating liquid while drawing the bonding wire through a bond tool from the bond pad to a package lead as recited in